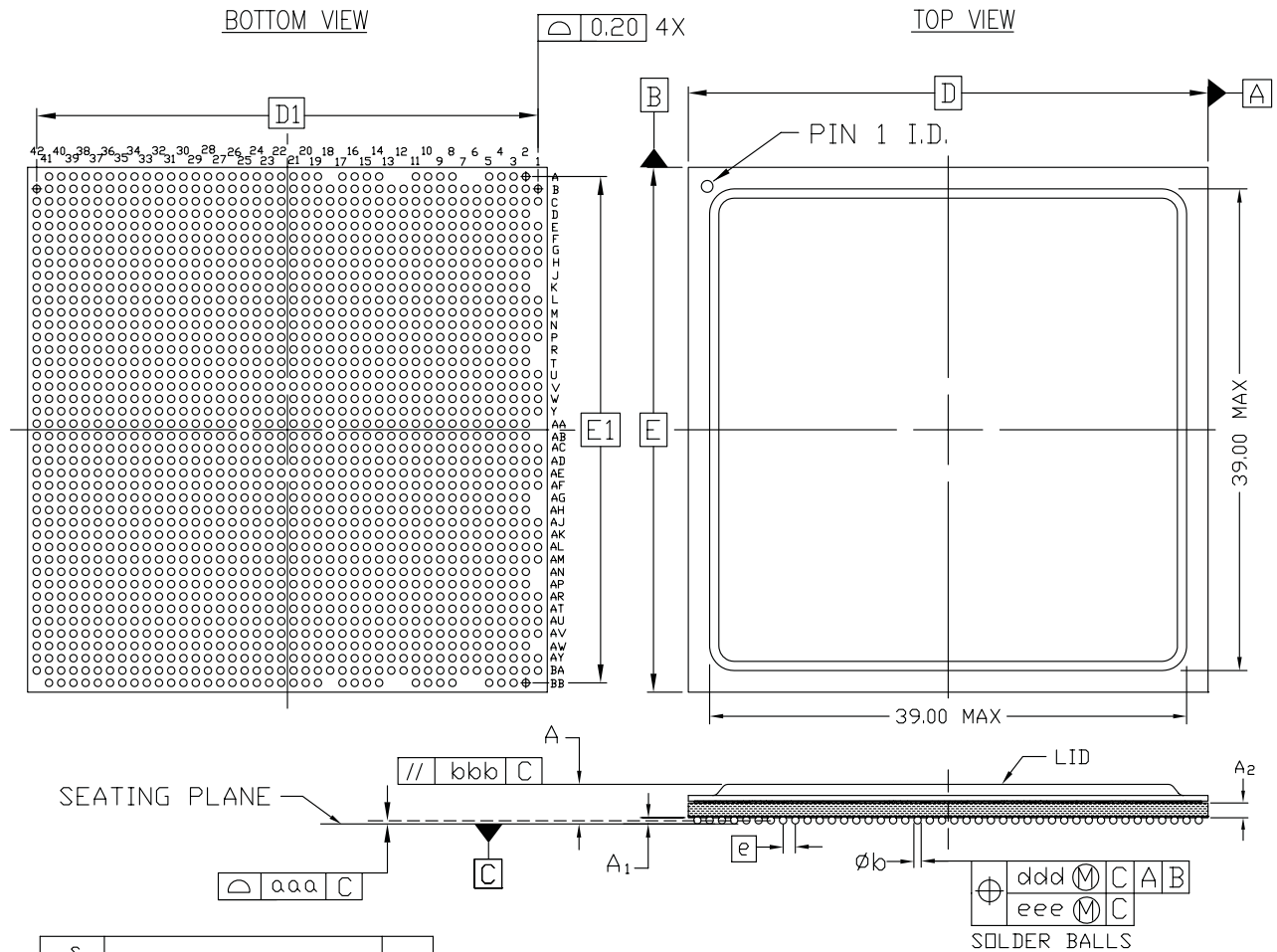


Flip-Chip BGA (FF1738) Package



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	2.70	<i>~</i>	3.50	2
A ₁	0.40	0.50	0.60	
A ₂	1.00	<i>~</i>	1.40	
D/E	42.50 BASIC			
D ₁ /E ₁	41.00 REF			
e	1.00 BASIC			
øb	0.50	0.60	0.70	
aaa	<i>~</i>	<i>~</i>	0.20	
bbb	<i>~</i>	<i>~</i>	0.25	
ddd	<i>~</i>	<i>~</i>	0.25	
eee	<i>~</i>	<i>~</i>	0.10	
M	42			

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
2. SYMBOL "M" IS THE PIN MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAV-1 (DEPOPULATED)

1738-BALL FLIP-CHIP BGA (FF1738)

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
07/13/07	1.0	Initial Xilinx release.